



# Digi XBee 3 BLU Development Kit

Complete Digi XBee 3 BLU development platform to integrate compact, flexible Bluetooth Low Energy connectivity for IoT devices

The **Digi XBee® 3 BLU Development Kit** offer an easy-to-use Bluetooth® development platform for designers, OEMs and solution providers supporting Bluetooth 5.4 Low Energy for industrial wireless IoT connectivity. The module supports an industrial temperature range of -40 °C to 85 °C (-40 °F to 185 °F) making it robust for a variety of industrial applications.

#### Pre-certified modules and tools for development

The pre-certified modules offer MicroPython programmability, beaconing, Bluetooth sensor support and the **Digi XBee Mobile App** to accelerate use in industrial wireless projects.

Standard Digi XBee API frames and AT commands, as well as MicroPython and **Digi XBee Studio**, make it simple to set up, configure and test modules or update their functionality.

Digi XBee Bluetooth Low Energy modules are a key offering in the **Digi XBee ecosystem** of wireless modules, adapters, tools and software — all engineered to accelerate product and application development, deployment and management.

Built-in **Digi TrustFence**\* security, identity and data privacy features use multiple layers of control to protect against new and evolving cyber threats. Bluetooth Low Energy also adds security via pairing & bonding, encrypted advertising along with existing XBee security including secure boot, hardware cryptographic acceleration and true random number generation.

#### Proven experience and expert support

Our decades of embedded experience and millions of deployed devices tell our story; Digi is a trusted solutions provider dedicated to simplifying the way OEMs design, build, deploy and maintain secure connected products.

**Digi Wireless Design Services** (WDS) provides additional connectivity integration support, certification assistance, and custom design and build services to get your products to market smarter and faster, and support you wherever you are along your development path.



Connect this device with

Digi XBee Studio.

Create. Configure. Deploy. Manage.

#### The kit includes:

- √ (1) Digi XBee 3 BLU modules: MMT with RF pad
- √ (1) XBIB interface boards
- √ Digi XBee Studio and Digi XBee Tools
- √ Additional documentation and examples

XK3-B5M-WBT Digi XBee 3 BLU Development Kit	PART NUMBER	DESCRIPTION
	XK3-B5M-WBT	Digi XBee 3 BLU Development Kit

#### Key features, benefits and applications

- Designed for a range of use cases, from maker projects to industrial applications
- Industrial-rated on a Bluetooth module
- Integrated MicroPython programmability for edge compute
- Bluetooth® Low Energy for beaconing, connecting to sensors and local configuration using the Digi XBee Mobile App
- Easily detect modules and connect to smart devices
- Low power consumption optimized for long battery life
- Integrated with Digi TrustFence security framework
- Manage with Digi XBee Studio and Digi IoT Mobile SDK
- Digi XBee API functionality and support
- Over-the-air (OTA) firmware updates with Digi XBee Mobile App
- Complete Bluetooth 5.4 Low Energy software stack



# Management and Configuration

#### **Digi XBee Studio**

Free multi-platform application that enables developers to manage Digi XBee devices through a simple-to-use graphical interface

**Digi XBee Studio** is the definitive tool to manage and configure Digi XBee devices. This next generation configuration tool suite supersedes **Digi XCTU**\* and offers an advanced set of tools that make it easy to set up, configure, communicate with and test Digi XBee modules and devices

The first thing you need to do in order to work with XBee devices in XBee Studio is to add them to the tool. In XBee Studio, this is easier than ever.

#### Simple setup and connectivity

Just after startup, XBee Studio will automatically look for XBee devices connected to your computer. As modules are found, they will appear in the Device Browser view. The Device Browser view displays all the devices connected to your computer.

#### View and manage your Digi XBee devices

View all of your Digi XBee devices in one table, or if they are geolocated, you can switch to the map view and see the location of each one.

Digi XBee Studio also offers a simple and step-by-step way to access and manage devices, including additional options for configuration, diagnostics, development, remote management and other utilities.

#### Proven experience and expert support

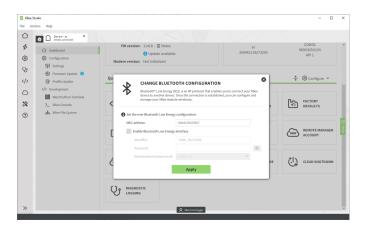
Our decades of embedded experience and millions of deployed devices tell our story; Digi is a trusted solutions provider dedicated to simplifying the way OEMs design, build, deploy and maintain secure connected products.

**Digi Wireless Design Services** (WDS) is an engineering team that provides additional connectivity integration support, certification assistance, and custom design and build services to get your products to market smarter and faster. The expert team of WDS engineers can support you wherever you are along your development path.



#### **Key features**

- Deploy on multiple platforms: Digi XBee Studio is compatible with the most popular operating systems, including Microsoft Windows, macOS and Linux.
- Discover your devices: Automatically discover XBee devices connected to your computer, regardless of their port connections or configured settings.
- Configure any device: Manage and configure multiple XBee devices at once, including devices enrolled in your Digi Remote Manager account located anywhere in the world.
- Communicate with your devices: Use the new smart XBee console to communicate with your devices regardless of whether they are configured for API mode or transparent mode..
- Access a range of tools: Use embedded tools to perform operations like creating XBee profiles or recovering your devices.
- Get automatic updates: Automatically update the application itself, as well as the radio firmware library, without downloading any extra files.





## Management and Security

#### Digi IoT Mobile SDK

**Digi IoT Mobile SDK** is a set of libraries, code examples and documentation designed to simplify the creation of iOS and Android mobile apps that interact with Digi XBee 3 BLU modules via Bluetooth.

Bluetooth enables local connectivity to Digi XBee modules via a mobile device to streamline network deployment, configuration and troubleshooting. Bluetooth Low Energy can also be used as a communication channel to create a Human Machine Interface (HMI) in a smartphone or tablet to monitor and control a device that does not have a display.

Digi IoT Mobile SDK helps speed up the development of mobile applications that interact with Digi XBee devices over the Bluetooth Low Energy interface. Access to the software libraries, examples and documentation can be found on the **Digi support site**.

Custom Bluetooth app examples include configuring Digi XBee firmware settings during deployment, exchanging data between a mobile application and a MicroPython application running on Digi XBee 3 BLU, or exchanging data between a mobile application and the host microcontroller.

Learn more at digi.com/xbee.

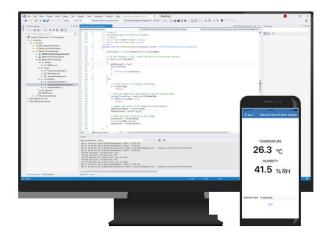
#### **Digi TrustFence**



#### Built-in security. Delivered.

Designed for mission-critical applications, **Digi TrustFence** enables users to easily integrate device security, device identity, and data privacy capabilities into product design. Digi TrustFence security for IoT devices is designed to grow and adapt with new and evolving threats.

Learn more at digi.com/trustfence.



# Create mobile applications that connect Digi XBee modules via Bluetooth

Digi IoT Mobile SDK includes:

- Well-documented APIs to handle the complexity of the Bluetooth authentication, encryption and communication processes
- Two libraries to simplify mobile app development:
  - A Digi XBee library for Xamarin, to develop native crossplatform (iOS and Android) mobile applications using C#
  - A Digi XBee library for Android, to develop native Android applications using Java
- Comprehensive documentation
- Example applications for both libraries

Download Digi IoT Mobile SDK:

https://hub.digi.com/support/products/digi-iot-mobile-sdk

Digi TrustFence is a device security framework that simplifies the process of securing connected devices.

- **Secure boot:** Programs and code running on the device are validated to be from an approved source or manufacturer.
- Protected hardware ports: Internal and external I/O ports are hardened and access-controlled to prevent unwanted intrusion.
- Authentication: TrustFence provides data authentication and device identity management options and ensures that products are not shipped with default user and password settings.
- Secure connections: These connections utilize the latest encryption protocols for data in motion and over-the-air (OTA) transmissions to ensure the integrity of network data.
- Ongoing monitoring and support: Digi provides ongoing threat measurement and monitoring services and performs external security audits.



# Digi XBee Ecosystem, Tools and Supporting Services

#### Digi XBee Ecosystem

The world-renowned XBee module is part of a family of cellular modems and RF modules that provide ultimate flexibility for IoT application developers, with three programmable form factors, and a range of popular wireless protocols. The XBee family also includes IoT gateways and management tools to connect, monitor and manage your XBee network. Learn more at digi.com/xbee.

# STOOL Build Deploy Manage Short Range Long Range Cellular Develop Build Deploy Manage CELLULAR Data Plans Digit TrustFence\*

#### **Digi XBee Tools**

The **Digi XBee Ecosystem** is fully supported with the award-winning **Digi XBee Tools** suite. Designed to support the full product lifecycle, from prototyping and development to deployment and ongoing monitoring, Digi XBee Tools includes code libraries, testing and prototyping tools, product development and manufacturing support, and tools for deploying and managing end devices in the field.









**DEVELOP** 

**BUILD** 

**DEPLOY** 

**MANAGE** 

#### **Digi Wireless Design Services**







**DEVELOPMENT** 



CERTIFICATION



MANUFACTURING

#### **Digi WDS Services**

We offer services to support you wherever you are along your development path, with a record that speaks for itself.

- Proof of concept
- Architecture consultation
- · Requirements definition
- System, software and electrical design
- · Design reviews
- Certifications
- Prototype build
- Manufacturing test fixtures
- 250+ product development projects
- 100+ certification failure rescues
- 100 million connected devices around the globe

#### Get to market faster with Digi WDS

**Digi Wireless Design Services** (WDS) has a proven history of helping clients speed down the path to success by guiding them through the technological and regulatory certification pitfalls that botch budgets and disrupt product introductions.

We begin by actively listening to your business and technical requirements, and then leverage our proven methodology, world-class engineering expertise and library of IP to design a cost-effective solution that is tailored to your specific needs. Accelerate toward the solution that is right for you and your customers.

Contact Digi WDS to find out how we can guide you to success.



# Specifications



Manage and configure Digi XBee 3 BLU modules with Digi XBee Studio

BLUETOOTH PERFORMANCE TRANSCEIVER CHIPSET Silicon Labs EFR32MG SoC	fications	Digi XBee 3 BLU
BLUETOOTH LOW ENERGY VERSION  Supports Bluetooth Low Energy 5.4 and capable of interoperating with Bluetooth Low Energy 5.4 devices that support M and 2M PHY  MAXIMUM RF DATA RATE  1 Mbps with 1M PHY and 2 Mbps with 2M PHY  INDOOR/URBAN RANGE*  Up to 15 m (49 ft)  OUTDOOR/RF LINE-OF-SIGHT RANGE*  Up to 300 m (984 ft)  TRANSMIT POWER  *8 dBm  RECEIVER SENSITIVITY  97 dBm  FEATURES  SERIAL DATA INTERFACE  UART, SPI  CONFIGURATION METHOD  API or AT commands, local or over-the-air (OTA)  FREQUENCY BAND  ISM 2.4 GHz  FORM FACTOR  Micro (MMT), through-hole (TH)  INTERFERENCE IMMUNITY  FSK (Frequency-shift keying)  ADC INPUTS  (4) 10-bit ADC inputs  DIGITAL I/O  13  ANTENNA OPTIONS  Micro: U.FL antenna, RF pad, chip antenna Through-hole: PCB antenna, U.FL connector  OPERATING TEMPERATURE  A"C: 13 mm x 19 mm x 2 mm (0.533 in x 0.76 in x 0.087 in) Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)  Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)		
MAXIMUM RF DATA RATE 1 Mbps with 1M PHY and 2 Mbps with 2M PHY  INDOOR/URBAN RANGE* Up to 15 m (49 ft)  OUTDOOR/RF LINE-OF-SIGHT RANGE* 12 to 15 m (49 ft)  OUTDOOR/RF LINE-OF-SIGHT RANGE* 148 dBm  RECEIVER SENSITIVITY -97 dBm  FEATURES  SERIAL DATA INTERFACE UART, SPI  CONFIGURATION METHOD API or AT commands, local or over-the-air (OTA)  FREQUENCY BAND ISM 2.4 GHz  FORM FACTOR Micro (MMT), through-hole (TH)  INTERFERENCE IMMUNITY FSK (Frequency-shift keying)  ADC INPUTS (4) 10-bit ADC inputs  DIGITAL I/O 13  ANTENNA OPTIONS Micro: U.FL antenna, RF pad, chip antenna Through-hole: PCB antenna, U.FL connector  OPERATING TEMPERATURE -40 °C to 85 °C (-40 °F to 185 °F)  DIMENSIONS Micro: 13 mm x 19 mm x 2 mm (0.533 in x 0.76 in x 0.087 in) Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)		Silicon Labs EFR32MG SoC
INDOOR/URBAN RANGE*  OUTDOOR/RF LINE-OF-SIGHT RANGE*  Up to 300 m (984 ft)  TRANSMIT POWER  +8 dBm  RECEIVER SENSITIVITY  -97 dBm  FEATURES  SERIAL DATA INTERFACE  UART, SPI  CONFIGURATION METHOD  API or AT commands, local or over-the-air (OTA)  FREQUENCY BAND  ISM 2.4 GHz  FORM FACTOR  Micro (MMT), through-hole (TH)  INTERFERENCE IMMUNITY  FSK (Frequency-shift keying)  ADC INPUTS  (4) 10-bit ADC inputs  DIGITAL I/O  ANTENNA OPTIONS  Micro: U.F.L antenna, RF pad, chip antenna Through-hole: PCB antenna, U.F.L connector  OPERATING TEMPERATURE  Micro: 13 mm x 19 mm x 2 mm (0.533 in x 0.76 in x 0.087 in) Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in) Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in) Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)	OOTH LOW ENERGY VERSION	Supports Bluetooth Low Energy 5.4 and capable of interoperating with Bluetooth Low Energy 5.4 devices that support 1M and 2M PHY
OUTDOOR/RF LINE-OF-SIGHT RANGE*  Up to 300 m (984 ft)  TRANSMIT POWER	JM RF DATA RATE	1 Mbps with 1M PHY and 2 Mbps with 2M PHY
RANGE* Up to 300 m (984 ft)  TRANSMIT POWER +8 dBm  RECEIVER SENSITIVITY -97 dBm  FEATURES  SERIAL DATA INTERFACE UART, SPI  CONFIGURATION METHOD API or AT commands, local or over-the-air (OTA)  FREQUENCY BAND ISM 2.4 GHZ  FORM FACTOR Micro (MMT), through-hole (TH)  INTERFERENCE IMMUNITY FSK (Frequency-shift keying)  ADC INPUTS (4) 10-bit ADC inputs  DIGITAL I/O 13  ANTENNA OPTIONS Micro: U.FL antenna, RF pad, chip antenna Through-hole: PCB antenna, U.FL connector  OPERATING TEMPERATURE -40 °C to 85 °C (-40 °F to 185 °F)  DIMENSIONS Micro: 13 mm x 19 mm x 2 mm (0.533 in x 0.76 in x 0.087 in) Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)	R/URBAN RANGE*	Up to 15 m (49 ft)
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SERIAL DATA INTERFACE  CONFIGURATION METHOD  API or AT commands, local or over-the-air (OTA)  FREQUENCY BAND  ISM 2.4 GHz  FORM FACTOR  Micro (MMT), through-hole (TH)  INTERFERENCE IMMUNITY  FSK (Frequency-shift keying)  ADC INPUTS  (4) 10-bit ADC inputs  DIGITAL I/O  13  ANTENNA OPTIONS  Micro: U.FL antenna, RF pad, chip antenna Through-hole: PCB antenna, U.FL connector  OPERATING TEMPERATURE  -40 °C to 85 °C (-40 °F to 185 °F)  DIMENSIONS  Micro: 13 mm x 19 mm x 2 mm (0.533 in x 0.76 in x 0.087 in) Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)	ER SENSITIVITY	-97 dBm
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FORM FACTOR  Micro (MMT), through-hole (TH)  INTERFERENCE IMMUNITY  FSK (Frequency-shift keying)  ADC INPUTS  (4) 10-bit ADC inputs  DIGITAL I/O  13  ANTENNA OPTIONS  Micro: U.FL antenna, RF pad, chip antenna Through-hole: PCB antenna, U.FL connector  OPERATING TEMPERATURE  -40 °C to 85 °C (-40 °F to 185 °F)  DIMENSIONS  Micro: 13 mm x 19 mm x 2 mm (0.533 in x 0.76 in x 0.087 in) Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)	JURATION METHOD	API or AT commands, local or over-the-air (OTA)
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ANTENNA OPTIONS  Micro: U.FL antenna, RF pad, chip antenna Through-hole: PCB antenna, U.FL connector  OPERATING TEMPERATURE  -40 °C to 85 °C (-40 °F to 185 °F)  DIMENSIONS  Micro: 13 mm x 19 mm x 2 mm (0.533 in x 0.76 in x 0.087 in) Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)	ERENCE IMMUNITY	FSK (Frequency-shift keying)
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ANTENNA OPTIONS         Through-hole: PCB antenna, U.FL connector           OPERATING TEMPERATURE         -40 °C to 85 °C (-40 °F to 185 °F)           DIMENSIONS         Micro: 13 mm x 19 mm x 2 mm (0.533 in x 0.76 in x 0.087 in)           Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)	_ I/O	13
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Through-hole: 2.438 cm x 2.761 cm (0.96 in x 1.087 in)	TING TEMPERATURE	-40 °C to 85 °C (-40 °F to 185 °F)
MEMORY 1 MB / 96 kB RAM	SIONS	· · · · · · · · · · · · · · · · · · ·
	ťΥ	1 MB / 96 kB RAM
NETWORKING AND SECURITY	KKING AND SECURITY	
PROTOCOL Bluetooth Low Energy 5.4	COL	Bluetooth Low Energy 5.4
ENCRYPTION 128/256-bit AES	PTION	128/256-bit AES
RELIABLE PACKET DELIVERY Retries/acknowledgements	LE PACKET DELIVERY	Retries/acknowledgements
IDS PAN ID and addresses, cluster IDs and endpoints (optional)		PAN ID and addresses, cluster IDs and endpoints (optional)
CHANNELS 40 channels	ELS	40 channels
SECURITY Digi TrustFence security with secure boot and protected JTAG	TY	Digi TrustFence security with secure boot and protected JTAG
CONFIGURATION TOOLS  Digi XBee Studio and Digi XBee Mobile App	JURATION TOOLS	Digi XBee Studio and Digi XBee Mobile App
EMBEDDED PROGRAMMABILITY MicroPython	DED PROGRAMMABILITY	MicroPython



# Specifications



Manage and configure Digi XBee 3 BLU modules with Digi XBee Studio

Specifications	Digi XBee 3 BLU
POWER REQUIREMENTS	
SUPPLY VOLTAGE	1.71 to 3.8 V
TRANSMIT CURRENT	32 mA at 3.3 V, +8 dBm
RECEIVE CURRENT	13.5 mA
IDLE CURRENT	7.5 mA
SLEEP CURRENT	8 μA at 25 °C (77 °F)
REGULATORY AND CARRIER APPROVALS**	
FCC, IC (NORTH AMERICA)	Complete
ETSI (EUROPE)	Complete
WARRANTY	
PRODUCT WARRANTY	1-year

<sup>\*</sup>Range figure estimates are based on free-air terrain with limited sources of interference. Actual range will vary based on transmitting power, orientation of transmitter and receiver, height of transmitting antenna, height of receiving antenna, weather conditions, interference sources in the area, and terrain between receiver and transmitter, including indoor and outdoor structures such as walls, trees, buildings, hills, and mountains.

<sup>\*</sup>Visit digi.com/resources/certifications for latest certifications and approvals.





### Part Numbers

Part Numbers	Digi XBee 3 BLU Development Kit
XK3-B5M-WBT	Digi XBee 3 BLU Development Kit

Part Numbers	Digi XBee 3 BLU
XB3-24B5UM-J	Digi XBee 3 BLU — Bluetooth Low Energy 5.4, U.FL, MMT
XB3-24B5CM-J	Digi XBee 3 BLU — Bluetooth Low Energy 5.4, chip antenna, MMT
XB3-24B5RM-J	Digi XBee 3 BLU — Bluetooth Low Energy 5.4, RF pad, MMT
XB3-24B5UT-J	Digi XBee 3 BLU — Bluetooth Low Energy 5.4, U.FL, TH
XB3-24B5PT-J	Digi XBee 3 BLU — Bluetooth Low Energy 5.4, PCB antenna, TH

# For more information, visit digi.com.



For more information about the Digi XBee 3 BLU Development Kit, visit digi.com/xbee-3-blu-kit.



877-912-3444 | 952-912-3444